



Product Summary

BV _{DSS}	BV _{DSS} R _{DS(ON)}	
30V	0.11Ω @ V _{GS} = 10V	4.7A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Audio Output Stage
- Relay and Solenoid Driving
- Motor Control



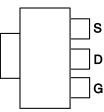
Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

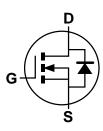
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 3
- Weight: 0.112 grams (Approximate)





Pin Out - Top



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXM62N03GTA	ZXM62N03	7	12	1,000
ZXM62N03GTC	ZXM62N03	13	12	4,000

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

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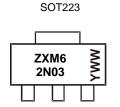
 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



 $\begin{array}{l} \text{ZXM62N03} = \text{Product Type Marking Code} \\ \text{YWW} = \text{Date Code Marking} \\ \text{Y or } \overline{\text{Y}} = \text{Last Digit of Year (ex: 5 = 2015)} \\ \text{WW or } \overline{\text{WW}} = \text{Week Code (01 to 53)} \end{array}$



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current ($V_{GS} = 10V, T_A = +25^{\circ}C$) (Note 6)		4.7	
(V _{GS} = 10V, T _A = +70°C) (Note 6)	I _D	3.8	А
(V _{GS} = 10V, T _A = +25°C) (Note 5)		3.4	
Pulsed Drain Current (Note 7)	I _{DM}	16	А
Continuous Source Current (Body Diode) (Note 6)	ls	2.6	А
Pulsed Source Current (Body Diode) (Note 7)	I _{SM}	16	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation at $T_A = +25^{\circ}C$ (Note 5) Linear Derating Factor	PD	2.0 16	W mW/°C
Power Dissipation at $T_A = +25^{\circ}C$ (Note 6) Linear Derating Factor	PD	3.9 31	W mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	62.5	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	32	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

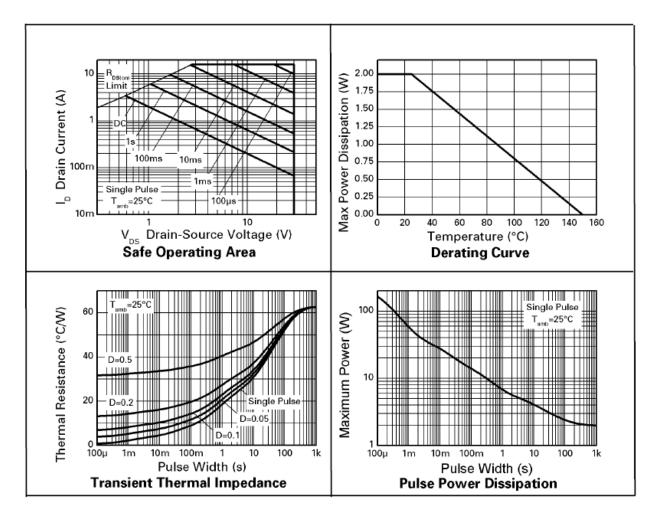
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	I _{DSS}	-	-	1	μA	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(TH)}	1	-	-	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance (Note 8)			-	0.11	Ω	$V_{GS} = 10V, I_D = 2.2A$	
Static Drain-Source On-Resistance (Note 6)	R _{DS(ON)}	-	-	0.15	12	V _{GS} = 4.5V, I _D = 1.1A	
Forward Transconductance (Notes 8 & 10)	g fs	1.1	-	-	S	$V_{DS} = 15V, I_D = 1.1A$	
Diode Forward Voltage (Note 8)	V _{SD}	-	-	0.95	V	$T_J = +25^{\circ}C, I_S = 2.2A,$ $V_{GS} = 0V$	
DYNAMIC CHARACTERISTICS (Note 10)			I			VGS – OV	
Input Capacitance	Ciss	-	380	-	pF	$V_{DS} = 25V, V_{GS} = 0V,$	
Output Capacitance	Coss	-	90	-	pF		
Reverse Transfer Capacitance	Crss	-	30	-	pF	- f = 1.0MHz	
Turn-On Delay Time (Note 9)	t _{D(ON)}	-	2.9	-	ns		
Turn-On Rise Time (Note 9)	t _R	-	5.6	-	ns	$V_{DD} = 15V, I_D = 2.2A, V_{GS} = 10V,$	
Turn-Off Delay Time (Note 9)	t _{D(OFF)}	-	11.7	-	ns	$R_{GS} = 6\Omega$	
Turn-Off Fall Time (Note 9)	t _F	-	6.4	-	ns		
Total Gate Charge (Note 9)	Qq	-	-	9.6	nC	V _{DS} = 24V, V _{GS} = 10V, I _D = 2.2A	
Gate-Source Charge (Note 9)	Q _{gs}	-	-	1.7	nC		
Gate-Drain Charge (Note 9)	Q _{qd}	-	-	2.8	nC		
Reverse Recovery Time	t _{RR}	-	18.8	-	ns	T _J = +25°C, I _F = 2.2A, di/dt =	
Reverse Recovery Charge	Q _{RR}	-	11.4	-	nC	100A/µs	

6. For a device surface mounted on FR-4 PCB measured at t \leq 10 seconds.

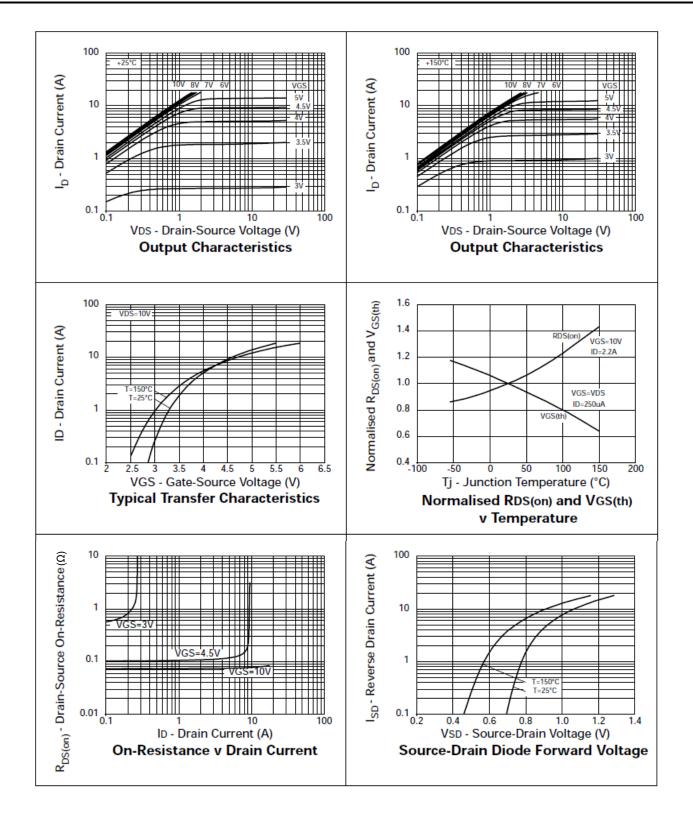
For a device surface mounted on FR-4 PCB measured at t≤ to seconds.
 Repetitive rating 25mm FR-4 PCB, D = 0.05 pulse width limited by maximum junction temperature.
 Measured under pulsed conditions. Width = 300µs. Duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperature.
 For design aid only, not subject to production testing.





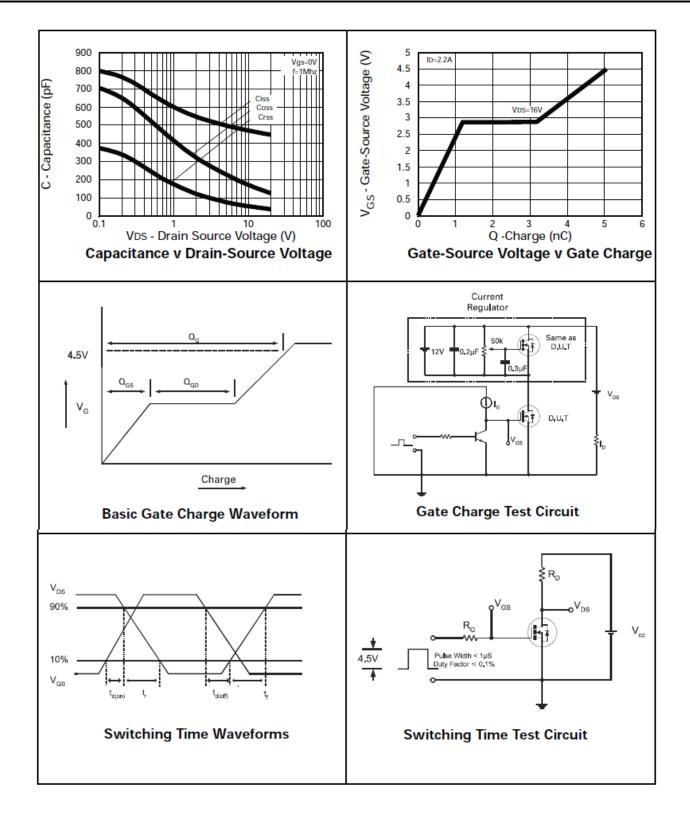


Typical Characteristics





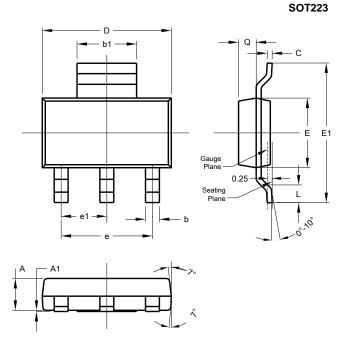
Typical Characteristics (Cont.)





Package Outline Dimensions

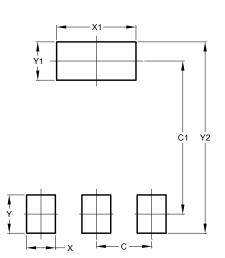
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT223				
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All [All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT223	

Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00



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